

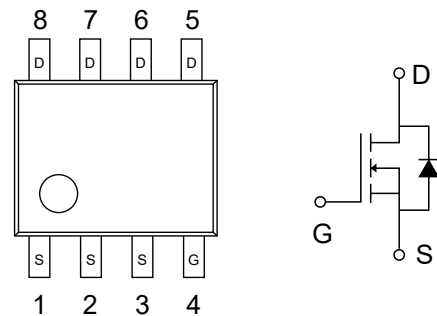
## 1.Description

The AO4406A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## 3.Pinning information

| Pin     | Symbol | Description |
|---------|--------|-------------|
| 4       | G      | GATE        |
| 1,2,3   | S      | SOURCE      |
| 5,6,7,8 | D      | DRAIN       |

SOP-8



## 4.Absolute Maximum Ratings

| Parameter                                        | Symbol               | Rating     | Units        |
|--------------------------------------------------|----------------------|------------|--------------|
| Drain-Source Voltage                             | $V_{DS}$             | 30         | V            |
| Gate-Source Voltage                              | $V_{GS}$             | $\pm 20$   | V            |
| Continuous Drain Current, $V_{GS}@10V^1$         | $I_D@T_A=25^\circ C$ | 12         | A            |
| Continuous Drain Current, $V_{GS}@10V^1$         | $I_D@T_A=70^\circ C$ | 8          | A            |
| Pulsed Drain Current <sup>2</sup>                | $I_{DM}$             | 30         | A            |
| Single Pulse Avalanche Energy <sup>3</sup>       | $E_{AS}$             | 20         | mJ           |
| Avalanche Current                                | $I_{AS}$             | 22         | A            |
| Total Power Dissipation <sup>4</sup>             | $P_D@T_A=25^\circ C$ | 4.5        | W            |
| Storage Temperature Range                        | $T_{STG}$            | -55 to 150 | $^\circ C$   |
| Operating Junction Temperature Range             | $T_J$                | -55 to 150 | $^\circ C$   |
| Thermal Resistance Junction-ambient <sup>1</sup> | $R_{\theta JA}$      | 50         | $^\circ C/W$ |
| Thermal Resistance Junction-Case <sup>1</sup>    | $R_{\theta JC}$      | 30         | $^\circ C/W$ |



## 5. Electrical Characteristic (T<sub>J</sub>=25°C unless otherwise noted)

| Parameter                                      | Symbol                              | Conditions                                                                             | Min | Typ   | Max  | Units |
|------------------------------------------------|-------------------------------------|----------------------------------------------------------------------------------------|-----|-------|------|-------|
| Drain-Source Breakdown Voltage                 | BV <sub>DSS</sub>                   | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA                                             | 30  |       |      | V     |
| BV <sub>DSS</sub> Temperature Coefficient      | ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | Reference to 25°C, I <sub>D</sub> =1mA                                                 |     | 0.027 |      | V/°C  |
| Static Drain-Source On-Resistance <sup>2</sup> | R <sub>DS(on)</sub>                 | V <sub>GS</sub> =10V, I <sub>D</sub> =10A                                              |     | 10    | 13   | mΩ    |
|                                                |                                     | V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A                                              |     | 12    | 16   |       |
| Gate Threshold Voltage                         | V <sub>GS(th)</sub>                 |                                                                                        | 1.2 | 1.5   | 2.5  | V     |
| V <sub>GS(th)</sub> Temperature Coefficient    | ΔV <sub>GS(th)</sub>                | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA                               |     | 5.8   |      | mV/°C |
| Drain-Source Leakage Current                   | I <sub>DSS</sub>                    | V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C                        |     |       | 1    | μA    |
|                                                |                                     | V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C                        |     |       | 5    |       |
| Gate-Source Leakage Current                    | I <sub>GSS</sub>                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                             |     |       | ±100 | nA    |
| Forward Transconductance                       | g <sub>FS</sub>                     | V <sub>DS</sub> =5V, I <sub>D</sub> =10A                                               |     | 5.8   |      | S     |
| Gate Resistance                                | R <sub>g</sub>                      | V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz                                       |     | 2.2   | 3.8  |       |
| Total Gate Charge (4.5V)                       | Q <sub>g</sub>                      | V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A                       |     | 12.6  | 17.6 | nC    |
| Gate-Source Charge                             | Q <sub>gs</sub>                     |                                                                                        |     | 4.2   | 5.9  |       |
| Gate-Drain Charge                              | Q <sub>gd</sub>                     |                                                                                        |     | 5.1   | 7.1  |       |
| Turn-On Delay Time                             | t <sub>D(on)</sub>                  | V <sub>DD</sub> =15V, V <sub>GS</sub> =10V<br>R <sub>G</sub> =3.3, I <sub>D</sub> =10A | 3.5 | 6.2   | 12.4 | ns    |
| Rise Time                                      | t <sub>r</sub>                      |                                                                                        |     | 59    | 106  |       |
| Turn-Off Delay Time                            | t <sub>D(off)</sub>                 |                                                                                        |     | 27.6  | 55   |       |
| Fall Time                                      | t <sub>f</sub>                      |                                                                                        |     | 8.4   | 16.8 |       |
| Input Capacitance                              | C <sub>iss</sub>                    | V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz                                      |     | 960   |      | pF    |
| Output Capacitance                             | C <sub>oss</sub>                    |                                                                                        |     | 139   |      |       |
| Reverse Transfer Capacitance                   | C <sub>rss</sub>                    |                                                                                        |     | 87    |      |       |
| Continuous Source Current <sup>1,5</sup>       | I <sub>S</sub>                      | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current                                      |     |       | 10.3 | A     |
| Pulsed Source Current <sup>2,5</sup>           | I <sub>SM</sub>                     |                                                                                        |     |       | 42   | A     |
| Diode Forward Voltage <sup>2</sup>             | V <sub>SD</sub>                     | V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C                          |     |       | 1.2  | V     |
| Reverse Recovery Time                          | t <sub>rr</sub>                     | I <sub>F</sub> =10A, dI/dt=100A/μs<br>T <sub>J</sub> =25°C                             |     | 12.5  |      | nS    |
| Reverse Recovery Charge                        | Q <sub>rr</sub>                     |                                                                                        |     | 5     |      | nC    |

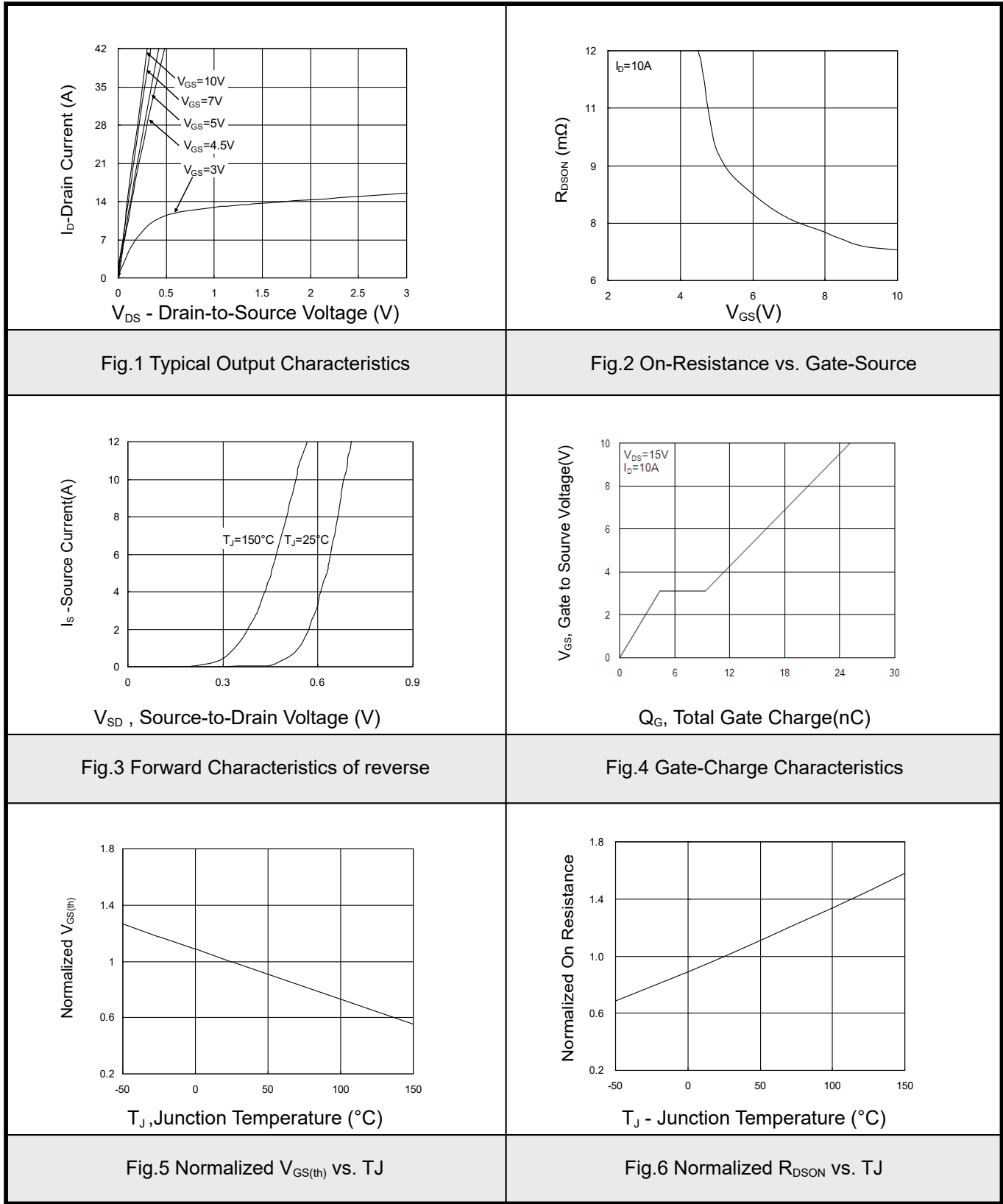


Nots:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=35A$ .
- 4.The power dissipation is limited by 150 °C junction temperature.
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.



6.1Typical characteristic





## 6.2 Typical characteristic

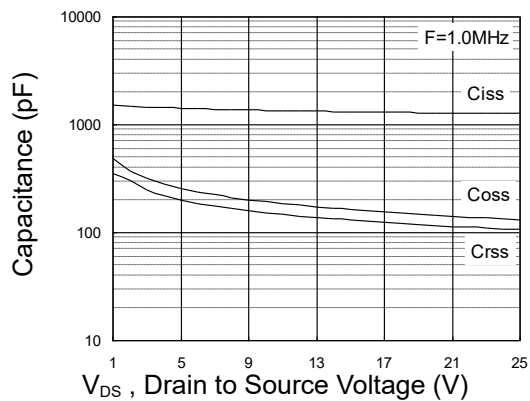


Fig.7 Capacitance

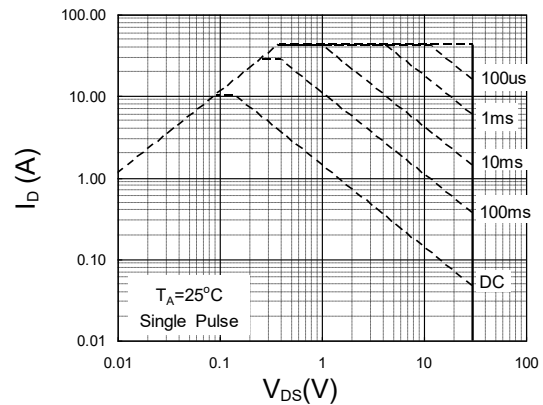


Fig.8 Safe Operating Area

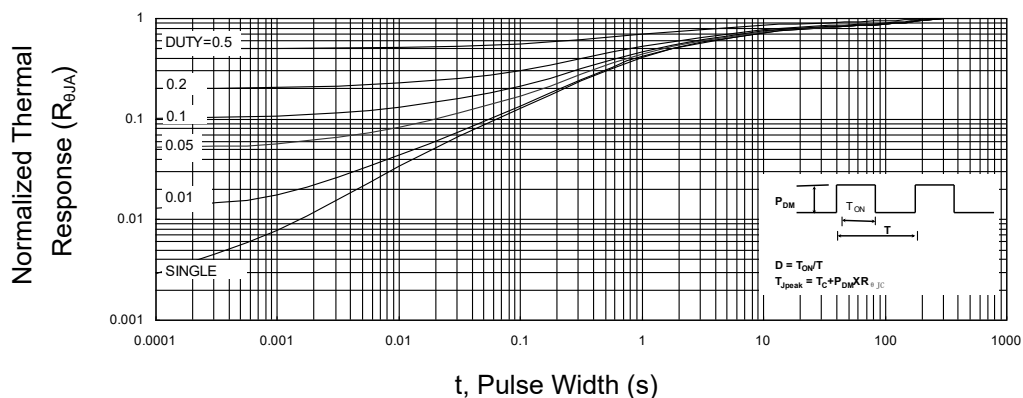


Fig.9 Normalized Maximum Transient Thermal Impedance

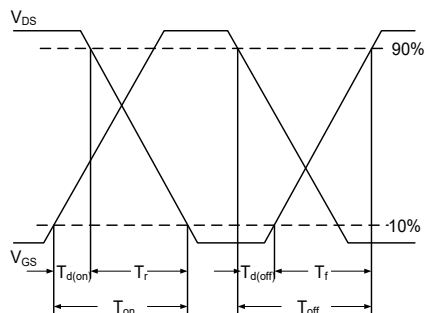


Fig.10 Switching Time Waveform

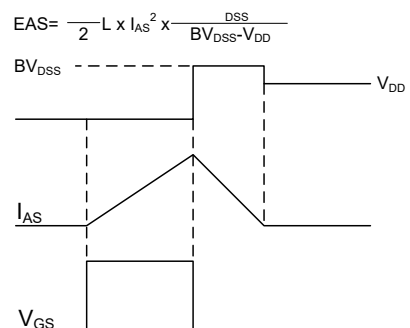
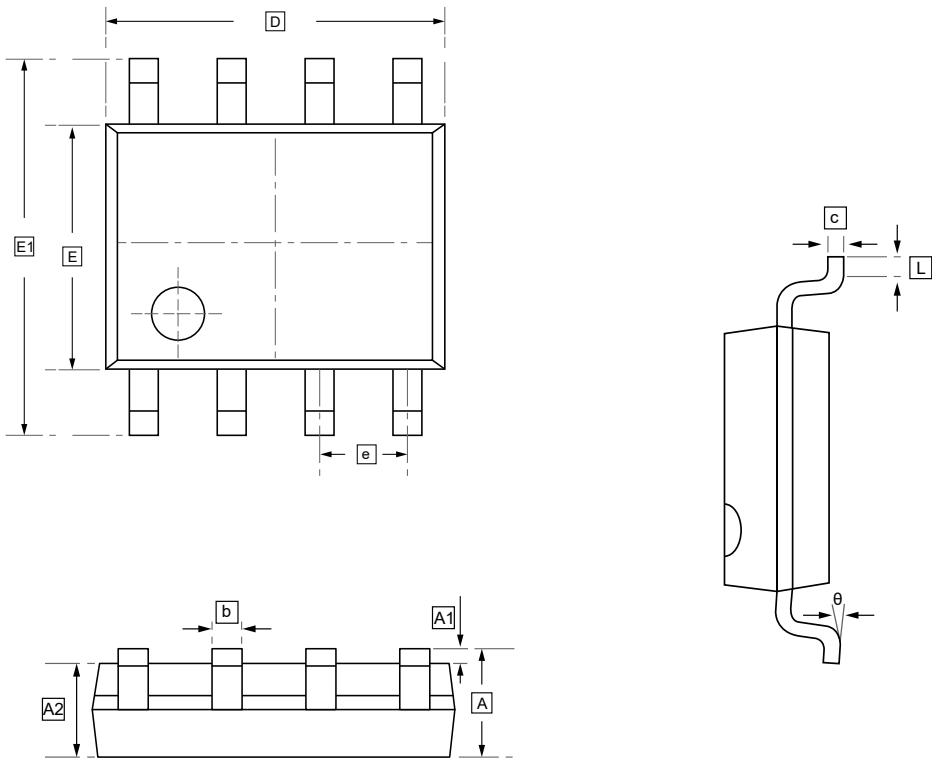


Fig.11 Unclamped Inductive Switching Waveform



7.SOP-8 Package Outline Dimensions

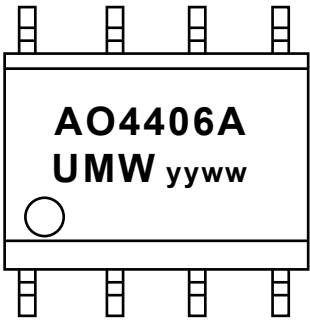


DIMENSIONS (mm are the original dimensions)

| Symbol | A     | A1    | A2    | b     | c     | D     | E     | E1    | e     | L     | θ  |
|--------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|----|
| Min    | 1.350 | 0.000 | 1.350 | 0.330 | 0.170 | 4.700 | 3.800 | 5.800 | 1.270 | 0.400 | 0° |
| Max    | 1.750 | 0.100 | 1.550 | 0.510 | 0.250 | 5.100 | 4.000 | 6.200 | BSC   | 1.270 | 8° |



8.Ordering information



yy: Year Code  
ww: Week Code

| Order Code  | Package | Base QTY | Delivery Mode |
|-------------|---------|----------|---------------|
| UMW AO4406A | SOP-8   | 3000     | Tape and reel |



## 9.Disclaimer

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